

<b>PCN Number:</b>	20190301000.1		<b>PCN Date:</b>	Mar 4 2019	
<b>Title:</b>	Qualification of TI Chengdu A/T (CDAT) as an Assembly and test site for Select Devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services		
<b>Proposed 1<sup>st</sup> Ship Date:</b>	June 4 2019	<b>Estimated Sample Availability:</b>	Date provided at sample request		
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of TI Chengdu (CDAT) as an Additional Assembly site for the list of devices shown below. Current assembly sites and Material differences are as follows:					
<b>Group 1 Devices:</b>					
		<b>Clark</b>	<b>CDAT</b>		
	Leadframe Prep	none	roughened		
	Mold compound	4208625	4222198		
	Mount Compound	4207768	4207123		
<b>Group 2 Devices:</b>					
		<b>Clark</b>	<b>CDAT</b>		
	Mold compound	4208625	4222198		
<b>Group 3 Devices:</b>					
		<b>Clark</b>	<b>UTAC</b>	<b>CDAT</b>	
	Mold compound	4208625	SID#CZ0134	4222198	
	Mount compound	4207123	SID#PZ0031	4207123	
	Lead Finish	NiPdAu	NiPdAuAg	NiPdAu	
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>		
<b>Changes to product identification resulting from this PCN:</b>					

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
TI Clark	QAB	PHL	Angeles City, Pampanga
UTAC	NSE	THA	Bangkok
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)





MADE IN: Malaysia  
2DC: 20:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO:USA  
(22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

**Group 1 Devices:**

MSP430FR58671IRGZR	MSP430FR5868IRGZR	MSP430FR5967IRGZR	MSP430FR59691IRGZR
MSP430FR58671IRGZT	MSP430FR5868IRGZT	MSP430FR5967IRGZT	MSP430FR59691IRGZT
MSP430FR5867IRGZR	MSP430FR5869IRGZR	MSP430FR5968IRGZR	MSP430FR5969IRGZR
MSP430FR5867IRGZT	MSP430FR5869IRGZT	MSP430FR5968IRGZT	MSP430FR5969IRGZT

**Group 2 Devices:**

TPS25740ARGER	TPS25740RGER	TPS25741ARSMR	TPS25741RSMR
TPS25740ARGET	TPS25740RGET	TPS25741ARSMT	TPS25741RSMT

**Group 3 Devices:**

CC2530F128RHAR	CC2531F256RHAT	CC2534RHAX	CC2541F256RHAR
CC2530F128RHAT	CC2533ARHAR	CC2540F128RHAR	CC2541F256RHAT
CC2530F12CRHA	CC2533CRHAR	CC2540F128RHAT	CC2541SRHAR
CC2530F256RHAR	CC2533F32RHAR	CC2540F256RHAR	CC2541SRHAT
CC2530F256RHAT	CC2533F32RHAT	CC2540F256RHAT	CC2570RHAR
CC2530F25CRHA	CC2533F64RHAR	CC2540F25ARHAR	CC2570RHAT
CC2530F32RHAR	CC2533F64RHAT	CC2540TF256RHAR	CC2571RHAR
CC2530F32RHAT	CC2533F96RHA	CC2540TF256RHAT	CC2571RHAT
CC2530F64RHAR	CC2533F96RHAR	CC2541CRHA	FRE008RHAR
CC2530F64RHAT	CC2533F96RHAT	CC2541CRHAR	FRE009RHAR
CC2531F128RHAR	CC2534RHA	CC2541F128RHAR	FRE010RHAR
CC2531F128RHAT	CC2534RHAR	CC2541F128RHAT	FRE015RHAR
CC2531F256RHAR	CC2534RHAT		

## Group 1 Devices Qual Memo:



TI Information  
Selective Disclosure

### Qualification Report

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: MSP430FR5969IRGZ	QBS Package Reference: MSP430FR2633IRHB
AC	Autoclave 121C	96 Hours	3/231/0	-
HAST	Biased HAST, 110C/85%RH	264 Hours	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
WBP	Bond Pull	Wires	3/228/0	-
WBS	Ball Bond Shear	Wires	3/228/0	-

- QBS: Qualification By Similarity
  - Qualification Device MSP430FR5969IRGZ is qualified at LEVEL2-260C
  - Preconditioning was performed for Autoclave, Biased HAST, Temperature Cycle, and High Temp. Storage Bake.
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

## Group 2 Devices Qual Memo:



TI Information  
Selective Disclosure

### Qualification Report

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS25725RSM	Qual Device: TPS25740ARGE	Qual Device: TPS25740RGE	Qual Device: TPS25741ARSM	Qual Device: TPS25741RSM	QBS Package Reference: TPS2231RGPR
AC	Autoclave 121C	96 Hours	-	-	-	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	Pass	-	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-
HBM	ESD - HBM	3000 V	-	1/3/0	-	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	-
HTOL	Life Test, 140C	480 Hours	-	-	-	-	-	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	-
HTOL	Life Test, 155C	240 Hours	-	-	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	500 Hours	-	-	-	-	-	-
LU	Latch-up (per JESD78)	-	-	1/6/0	-	-	1/6/0	-
PD	Physical Dimensions	--	-	-	-	-	-	3/15/0
SD	Solderability	8 Hours Steam Age	-	-	-	-	-	3/66/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	-	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	-	3/231/0
TS	Thermal Shock -65/150C	500 Cycles	-	-	-	-	-	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-
WBP	Bond Pull	Wires	-	-	-	-	-	3/228/0
WBS	Bond Shear	Wires	-	-	-	-	-	3/228/0
YLD	FTY and Bin Summary	--	Pass	Pass	Pass	Pass	Pass	-

- QBS: Qual By Similarity
  - Qual Devices qualified at LEVEL2-260CG: TPS25740RGE, TPS25741RSM, TPS25725RSM, TPS25740ARGE, TPS25741ARSM
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

#### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

## Group 3 Devices Qual Memo:



TI Information  
Selective Disclosure

### Qualification Report

#### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CC2540F256RHAR	QBS Package Reference: MSP430F5172IRSB
AC	Autoclave 121C	96 Hours	1/77/0	3/231/0
HAST	Biased HAST, 110C/85%RH	264 Hours	-	3/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	3/231/0
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0

- QBS: Qual By Similarity

- Qual Device CC2540F256RHAR is qualified at LEVEL3-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>